



Material Content Data Sheet



Sales Product Name		IPB054N06N3 G		Issued		29. August 2013			
MA#		MA000472914							
Package		PG-TO263-3-2		Weight*		1462.29 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	3.393	0.23	0.23	2321	2321	
leadframe	non noble metal	iron	7439-89-6	0.853	0.06		583		
	inorganic material	phosphorus	7723-14-0	0.256	0.02		175		
	non noble metal	copper	7440-50-8	851.691	58.25	58.33	582438	583196	
wire	non noble metal	aluminium	7429-90-5	5.162	0.35	0.35	3530	3530	
encapsulation	organic material	carbon black	1333-86-4	8.829	0.60		6038		
	plastics	epoxy resin	-	97.117	6.64		66414		
	inorganic material	silicondioxide	60676-86-0	482.641	33.01	40.25	330060	402512	
leadfinish	non noble metal	tin	7440-31-5	9.657	0.66	0.66	6604	6604	
plating	non noble metal	nickel	7440-02-0	0.228	0.02		156		
	inorganic material	phosphorus	7723-14-0	0.001	0.00	0.02	0	156	
solder	noble metal	silver	7440-22-4	0.061	0.00		42		
	non noble metal	tin	7440-31-5	0.049	0.00		34		
	non noble metal	lead	7439-92-1	2.347	0.16	0.16	1605	1681	
*deviation	< 10%					Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com